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Ajinomoto Build-up Film Market by Application (Advanced Semiconductor Package Substrate, Organic Interposer, Fan-out Packaging, High-density Interconnect (HDI), and Ultra-HDI Printed Circuit Board (PCBs)) - Global Forecast to 2032

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Abstracts

The global Ajinomoto build-up film market is valued at USD 11.56 billion in 2026 and is projected to reach USD 49.63 billion by 2032, registering a CAGR of 27.5% during the forecast period. The rapid growth in electric vehicle manufacturing is emerging as a strong driver of demand for Ajinomoto build-up films in automotive semiconductor applications. Electric vehicles incorporate significantly higher semiconductor content than internal combustion engine vehicles, driven by battery management systems, power electronics, advanced driver assistance systems, infotainment, and vehicle connectivity. These systems operate under demanding conditions, including high temperatures, voltage fluctuations, and continuous mechanical stress. ABF materials are used in advanced IC substrates that provide thermal stability, electrical insulation, and long-term reliability required for such environments. This supports sustained growth in automotive-grade ABF usage, further strengthened by emission regulations, government incentives for electric vehicles, and ongoing investment in vehicle electrification and software-driven architectures. In addition, demand for high-performance computing, artificial intelligence, cloud services, and data center infrastructure continues to grow rapidly. These applications require semiconductor chips with higher layer counts and improved performance, which drives the adoption of ABF material to support more complex and reliable packaging structures.

“Fan-out packaging segment is expected to grow at the second-fastest CAGR during the forecast period.”

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Fan-out packaging redistributes chip input/output connections to achieve higher integration density and improved electrical performance. ABF dielectric layers support high-density redistribution layers and advanced semiconductor package structures in fan-out packaging technologies. The increasing demand for compact and high-performance semiconductor packages is accelerating the adoption of fan-out packaging solutions. The evolution of semiconductor design toward modular architecture and higher functional integration is further supporting the expansion of fan-out technologies. Industry participants are increasingly adopting fan-out approaches to address mid-range performance requirements. Ongoing investments in process scalability, panel-level packaging, and advanced redistribution techniques are expected to reinforce the segment's growth trajectory, establishing fan-out packaging as a critical bridge between traditional packaging and next-generation integration approaches within the ABF ecosystem.

"Europe is expected to grow at the second-fastest CAGR during the forecast period."

Europe is expected to register the second-fastest CAGR in the Ajinomoto build-up film market, driven by its increasing focus on strengthening semiconductor sovereignty and advancing regional chip manufacturing capabilities. The region is witnessing rising investments in semiconductor R&D, advanced packaging technologies, and substrate innovation, supported by policy initiatives such as the European Chips Act. These efforts aim to reduce dependence on external supply chains while fostering a resilient and competitive semiconductor ecosystem. Europe is a key market for Ajinomoto build-up film, supported by strong demand from the region's automotive electronics and industrial automation sectors, as well as leading semiconductor equipment and automotive technology companies that drive adoption of advanced packaging substrates for high-performance semiconductor devices. Growing electrification in the automotive sector, including electric vehicles and ADAS systems, is increasing demand for high-performance semiconductor components that require advanced packaging materials such as ABF.

By Company Type: Tier 1 – 45%, Tier 2 – 35%, and Tier 3 – 20%

By Designation: Sales & Marketing Heads/Directors – 35%, Regional & Global Business Unit Heads – 30%, Market Intelligence & Strategy Leads – 25, and Others – 10%

By Region: North America – 37%, Europe – 36%, Asia Pacific – 22%, and RoW

– 5%

Prominent players profiled in this report include Ajinomoto Co., Inc. (Japan), Sekisui Chemical Co., Ltd. (Japan), Waferchem Technology (Taiwan), Taiyo Holdings Co., Ltd. (Japan), and Nippon Kayaku Co., Ltd. (Japan), among others.

Research Coverage:

The report defines, describes, and forecasts the Ajinomoto build-up film market based on application (advanced semiconductor package substrates, organic interposers, fan-out packaging, and high-density interconnect (HDI) and ultra-HDI printed circuit boards (PCBs)) and region (North America, Europe, Asia Pacific, and RoW). It provides detailed information regarding drivers, restraints, opportunities, and challenges influencing the market's growth. It also analyzes competitive developments, including acquisitions, product launches, expansions, and strategic initiatives undertaken by key players to strengthen their market positions.

Reasons to Buy This Report:

The report will help market leaders/new entrants with information on the closest approximations of the revenue for the overall Ajinomoto build-up film market and its subsegments. The report will help stakeholders understand the competitive landscape and gain deeper insights to better position their business and plan effective go-to-market strategies. The report also helps stakeholders understand the market dynamics and provides information on key drivers, restraints, opportunities, and challenges.

The report will provide insights into the following points:

Analysis of key drivers (surging demand for advanced semiconductor packaging in high-performance computing and increasing demand from consumer electronics and mobile devices), opportunities (capacity expansion and strategic investments in semiconductor packaging and increasing semiconductor demand from electric vehicles), and challenges (exposure to semiconductor demand cycles) of the Ajinomoto build-up film market.

Product Development/Innovation: Detailed insights into emerging technologies, advancements in semiconductor build-up film, and ongoing research & development activities in the Ajinomoto build-up film market.

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Market Development: Comprehensive information about lucrative markets. The report analyzes the Ajinomoto build-up film market across various regions.

Market Diversification: Exhaustive information about new product developments, untapped application areas, recent industry developments, and investments in the Ajinomoto build-up film market.

Competitive Assessment: In-depth assessment of market share, growth strategies, and offerings of leading players, including Ajinomoto Co., Inc. (Japan), Sekisui Chemical Co., Ltd. (Japan), Waferchem Technology (Taiwan), Taiyo Holdings Co., Ltd (Japan), and Nippon Kayaku Co., Ltd. (Japan), among others.

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Contents

1. INTRODUCTION

1.1. KEY TAKEAWAYS
1.2. STUDY SCOPE
1.3. MARKET SCOPE
  1.3.1. MARKETS COVERED AND REGIONAL SCOPE
  1.3.2. INCLUSIONS AND EXCLUSIONS
  1.3.3. YEARS CONSIDERED FOR STUDY

2. RESEARCH METHODOLOGY

2.1. RESEARCH DATA
  2.1.1. SECONDARY DATA
  2.1.2. PRIMARY DATA
    2.1.2.1. BREAKDOWN OF PRIMARIES
2.2. RESEARCH METHODOLOGY
2.3. MARKET SIZE ESTIMATION
2.4. INDUSTRY-SPECIFIC MARKET SIZE ESTIMATION

3. EXECUTIVE SUMMARY

3.1. MARKET HIGHLIGHTS AND KEY INSIGHTS
3.2. MARKET SNAPSHOT: MARKET SIZE, GROWTH RATE, AND FORECAST
  3.2.1. BY APPLICATION
  3.2.2. BY REGION

4. PREMIUM INSIGHTS

4.1. ATTRACTIVE OPPORTUNITIES FOR PLAYERS IN AJINOMOTO BUILD-UP FILM MARKET
4.2. AJINOMOTO BUILD-UP FILM MARKET: BREAKDOWN OF GROWTH RATE BASED ON COUNTRY DURING FORECAST PERIOD

5. MARKET OVERVIEW

5.1. MARKET DYNAMICS
5.2. TECHNOLOGY TRENDS/DISRUPTIONS IMPACTING CUSTOMER'S BUSINESS

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5.3. SUPPLY CHAIN & ECOSYSTEM ANALYSIS
5.4. ECOSYSTEM ANALYSIS
5.5. PATENT ANALYSIS
5.6. TRADE ANALYSIS
5.7. PORTER'S FIVE FORCES ANALYSIS

6. AJINOMOTO BUILD-UP FILM MARKET, BY APPLICATION

6.1. INTRODUCTION 6.2. ADVANCED SEMICONDUCTOR PACKAGE SUBSTRATES
6.3. ORGANIC INTERPOSERS
6.4. FAN-OUT PACKAGING
6.5. HIGH-DENSITY INTERCONNECT (HDI) AND ULTRA-HDI PRINTED CIRCUIT BOARDS (PCBS)

7. AJINOMOTO BUILD-UP FILM MARKET, BY REGION

7.1. INTRODUCTION
7.2. NORTH AMERICA
  7.2.1. US
  7.2.2. CANADA
  7.2.3. MEXICO
7.3. EUROPE
  7.3.1. GERMANY
  7.3.2. FRANCE
  7.3.3. UK
  7.3.4. ITALY
  7.3.5. SPAIN
  7.3.6. REST OF EUROPE
7.4. ASIA PACIFIC
  7.4.1. CHINA 7.4.2. JAPAN
  7.4.3. INDIA
  7.4.4. SOUTH KOREA
  7.4.5. REST OF ASIA PACIFIC
7.5. ROW

8. COMPETITIVE LANDSCAPE

8.1. REVENUE ANALYSIS 8.2. MARKET SHARE ANALYSIS, 2025
8.3. COMPETITIVE SCENARIO

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8.3.1. PRODUCT LAUNCHES
8.3.2. DEALS

9. COMPANY PROFILES 9.1. KEY PLAYERS

9.1.1. AJINOMOTO CO., INC.
9.1.2. SEKISUI CHEMICAL CO., LTD.
9.1.3. WAFERCHEM TECHNOLOGY
9.1.4. TAIYO HOLDINGS CO., LTD. 9.1.5. WUHAN SANXUAN TECHNOLOGY
9.1.6. NIPPON KAYAKU
9.1.7. RESONAC HOLDINGS CORPORATION
9.1.8. JSR CORPORATION
9.1.9. MITSUBISHI CHEMICAL
9.1.10. TORAY
9.2. OTHER PLAYERS

10. APPENDIX

10.1. KNOWLEDGESTORE: MARKETSANDMARKETS' SUBSCRIPTION PORTAL
10.2. AUTHOR DETAILS

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